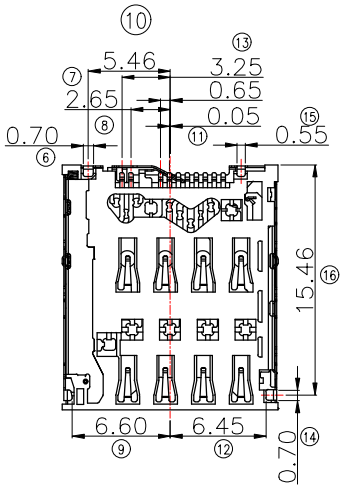
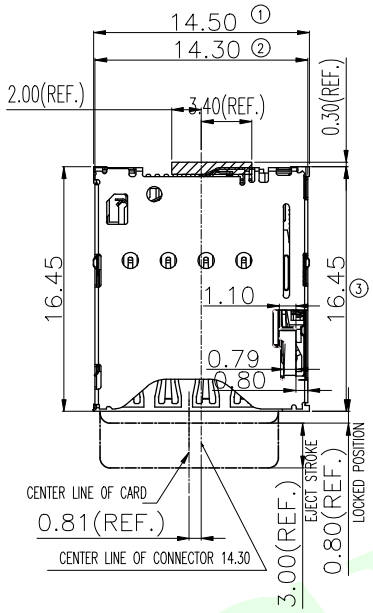
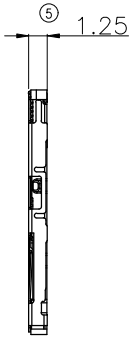
RoHS Compliant



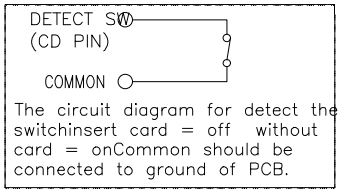




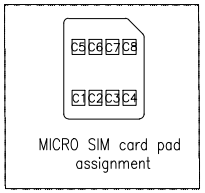
PIN NO.	PIN ASSIGNMENT
C1	SUPPLY VOLTAGE(VCC)
C2	RESET(RST)
C3	CLOCK(CLK)
C4	RESERVED FOR FUTURE USE(RFU)
C5	GROUND(GND)
C6	PROGRAMMING VOLTAGE(VPP)
C7	I/O
C8	RESERVED FOR FUTURE USE(RFU)

SPECIFICATIONS:
1.ELECTRICAL CHARACTERISTICS:
1-1. CURRENT RATING: 1A
1-2. CONTACT RESISTANCE:
1-2-1. 100mΩ MAX. (INITIAL) (FOR C1/C2/C3/C4/C5/C6/C7/C8)
1-2-2. 500mΩ MAX. (INITIAL) (FOR CD/COMMON)
1-3. DIELECTRIC WITHSTANDING VOLTAGE: 500V AC FOR ONE MINUTE.
1-4. INSULATION RESISTANCE: 100MΩ MIN. BY 500V DC.
2. MECHANICAL CHARACTERISTICS:
2-1. LIFE TEST: 5000 CYCLES MIN.
3. ENVIRONMENTAL CHARACTERISTICS:
3-1. SALT MIST TEST CONDITION: PER IEC 68-2-52, SEVERITY(3)
3-2. OPERATING TEMPERATURE: -30°~+80°
3-3. TO CONFORM TO SINGATRON HAZARDOUS SUBSTANCE FREE SPEC.
3-4. RoHS COMPLIANT PRODUCT.
3-5. HALOGEN FREE PRODUCT IDENTIFICATION MARK:
3-6. HALOGEN FREE PRODUCT IDENTIFICATION LABEL ON PACKAGING:

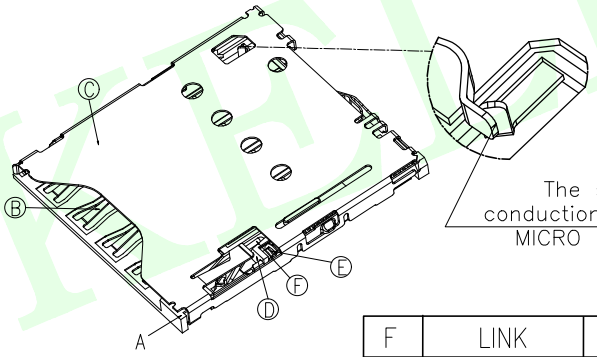
4. OTHER GENERAL SPEC. TO REFER "2SM2019 SERIES SPEC."
5. FOR REFLOW SOLDERING LEAD-FREE PROCESS.
6. PACKAGING: TAPE & REEL.



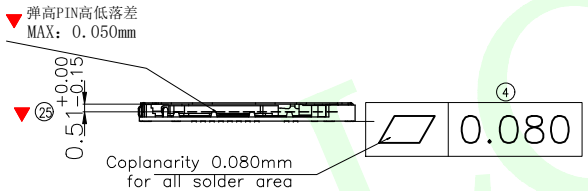
The circuit diagram for detect the switchinsert card = off without card = onCommon should be connected to ground of PCB.

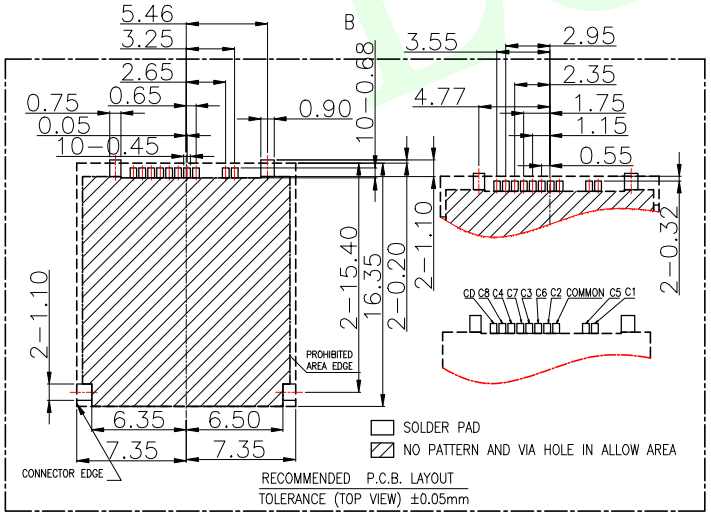


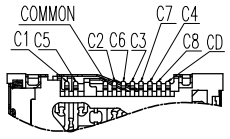
MICRO SIM card pad assignment

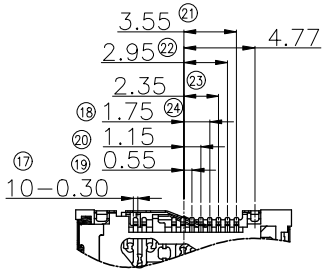


The switch is conduction without MICRO SIM card









F	LINK	1	STAINLESS STEEL T=0.10	N/A
E	SPRING	1	SWP	NICKEL PLATING
D	SLIDE	1	HIGH TEMP.THERMOPLASTIC,UL94V-0 AND STAINLESS STEEL	BLACK
C	SHELL	1	SUS 301 1/2H T=0.1	NICKEL PLATING
B	CONTACT	1	C5210 EH T=0.10 4SM2019-002002	3u" GOLD PLATING ONCONTACT AREA AND SOLDER AREA ,50u" MIN NICKEL UNDER PLATING
A	HOUSING	1	LCP+35%GF S475 UL94V-0	BLACK

MEASURE POINT:
QUADRANT POINT (QP)
TANGERCY POINT (TP)
INTERSECTION POINT (IP)

UNLESS OTHERWISE SPECIFIED,TOLERANCE:
X. ±0.25
X.x ±0.20
X.xx ±0.15
ANGULAR ±3°

联晟欣连接器（深圳）有限公司
Lianshengxin Connector (Shenzhen) Co., Ltd

DESIGN	Andy	DATE	2014.12.24
CHECKED		DATE	
APPROVED		DATE	

TITLE: MICRO SIM CARD 1.25H CONNECTOR

PART NO: LCK-SIM-005P10H125-WLG	REV: 04	SCALE: 1:1	UNIT: mm
DRAWING NO: 1020221025	SIZE: A4	SHEET: 1/1	

LCHELEC